



## ASSEMBLY CLEAN® PRODUCT DESCRIPTION



## **GENERAL**

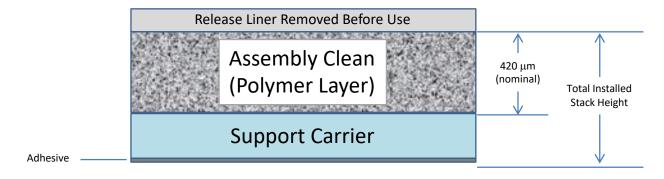
Assembly Clean® is designed to remove loose debris, which is generated during the assembly process and stuck to the pick and place hardware. It is not designed to remove embedded or bonded debris. The removal of embedded or bonded debris requires abrasive products such as Probe Polish®.

Regular use of Assembly Clean® in assembly equipment such as die attach extends the time between when abrasive cleaning may be required. The collet and other pick and place fixture cleaning frequency and number of cleaning insertions varies according to the specific environment.

The cleaning motion with Assembly Clean® is only in the Z direction. No lateral forces are applied to the fixture. The forces exerted on the fixture when cleaning with Assembly Clean® are far less than the forces as during normal operations.

The Assembly Clean® polymer collects and traps the debris generated during cleaning. Reuse of the cleaning pad will cause the trapped debris to be pushed deeper into the polymer. Visually check the pad from time to time to ensure that it does not become over-loaded with debris, which reduce the cleaning performance of the material. To achieve maximum cleaning efficiency, offset each touchdown location approximately 2X the probe diameter in the XY directions, such that probe tip always touches the clean surface of the cleaning material.

## **CROSS SECTION**



	Cleaning Material Configuration			
	Sheet	200mm Wafer	300mm Wafer	Custom Install
Polymer Layer Thickness	420 μm (nominal)	420 μm (nominal)	420 μm (nominal)	Contact ITS
Support Carrier	145 μm (PET nominal)	725 ± 20μm (SEMI Standard)	775 ± 20μm (SEMI Standard)	Contact ITS
Total Installed Stack Height	565 ± 20μm	1145 ± 40μm	1195± 40 μm	Contact ITS

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